

## P-Channel Enhancement Mode Field Effect Transistor

### General Description

Product Summary		
$V_{DSS}$	$I_D$	$R_{DS(ON)}(m\Omega)TYP$
-20V	-3.6A	95 @ $V_{GS}=-4.5V$
		115 @ $V_{GS}=-2.5V$

### Features

- Super high dense cell design for low  $R_{DS(ON)}$
- Rugged and reliable
- Simple drive requirement
- SOT-23-3L/B package

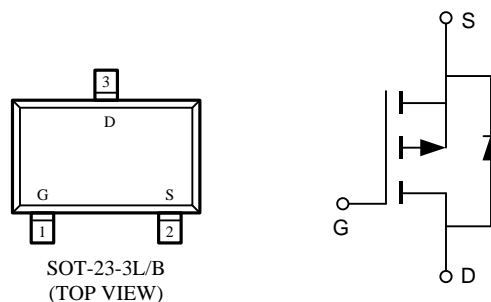
### Package

- SOT-23-3L/B

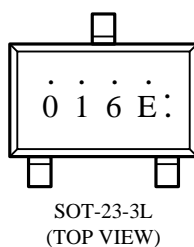
### Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
LN2301	-55°C to +150°C	SOT-23-3L/B	3000

### Pin Configuration



### Marking Rule



**Notes:** "•" represents the batch number. "•" "says" 1", dot not said "0"; For example: dot on the top of the "6", and the top right of the "E", said "010010", used to track the product batch.

**■ Absolute Maximum Ratings**

(TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	-20	V
Gate-source voltage	$V_{GS}$	±12	V
Drain current-continuous <sup>a</sup> @Tj=125°C -pulse <sup>b</sup>	$I_D$	-3.6	A
	$I_{DM}$	-11	A
Drain-source Diode forward current	$I_S$	-1.25	A
Maximum power dissipation	$P_D$	1.25	W
Operating junction Temperature range	$T_j$	-55—150	°C

**Electrical Characteristics**

(TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-20	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V	-	-	-1	μA
Gate-body leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±10V	-	-	±100	nA
<b>ON Characteristics</b>						
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.5	-0.8	-1.5	V
Drain-source on-state resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2.8A	-	95	110	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-2.0A	-	115	145	
Forward transconductance	g <sub>fs</sub>	V <sub>GS</sub> =-5V, I <sub>D</sub> =-5A	-	5	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V f=1.0MHz	-	586	-	pF
Output capacitance	C <sub>OSS</sub>		-	101	-	
Reverse transfer capacitance	C <sub>RSS</sub>		-	59	-	
<b>Switching Characteristics</b>						
Turn-on delay time	t <sub>D(ON)</sub>	V <sub>DD</sub> =-10V I <sub>D</sub> =-2.8A V <sub>GEN</sub> =-4.5V R <sub>L</sub> =10ohm R <sub>GEN</sub> =-60ohm	-	6.5	-	ns
Rise time	t <sub>r</sub>		-	32.1	-	
Turn-off delay time	t <sub>D(OFF)</sub>		-	58.4	-	
Fall time	t <sub>f</sub>		-	48	-	
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-3A V <sub>GS</sub> =-4.5V	-	6	-	nC
Gate-source charge	Q <sub>gs</sub>		-	1.35	-	
Gate-drain charge	Q <sub>gd</sub>		-	1.5	-	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =-1.25A	-	-0.81	-1.2	V

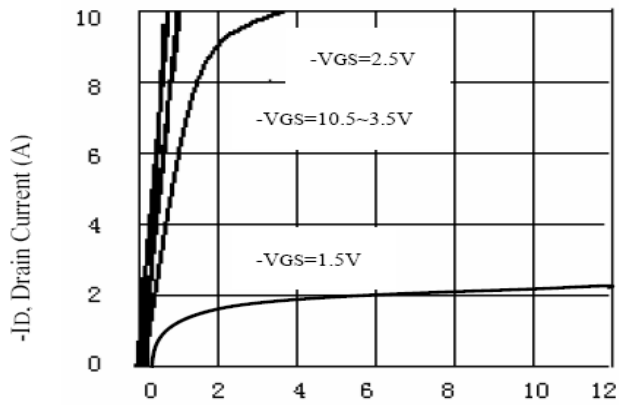
**Notes:**

- surface mounted on FR4 board, t<sub>s</sub>≤10sec
- pulse test: pulse width≤300μs, duty≤2%
- guaranteed by design, not subject to production testing

**Thermal Characteristics**

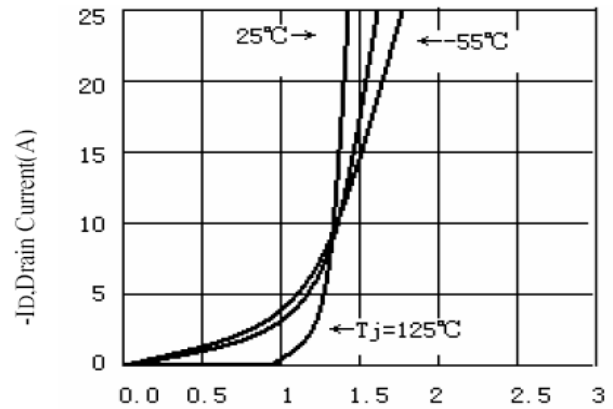
Thermal Resistance junction-to ambient	R <sub>th JA</sub>	100	°C/W
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■ Typical Performance Characteristics



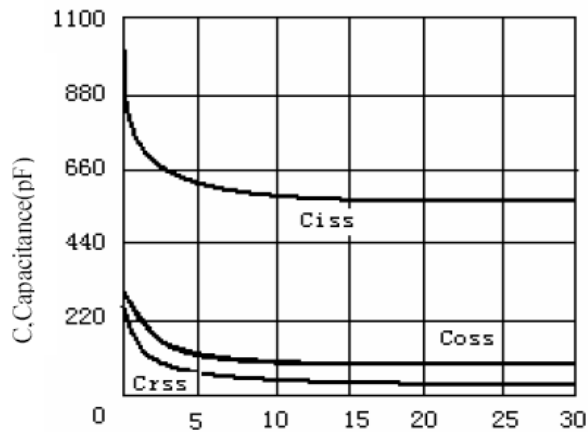
-  $V_{DS}$ , Drain-to-Source Voltage (V)

Figure 1. Output Characteristics



-  $V_{GS}$ , Gate-to-source Voltage (V)

Figure 2. Transfer Characteristics



-  $V_{GS}$ , Drain-to Source Voltage

Figure3. Capacitance

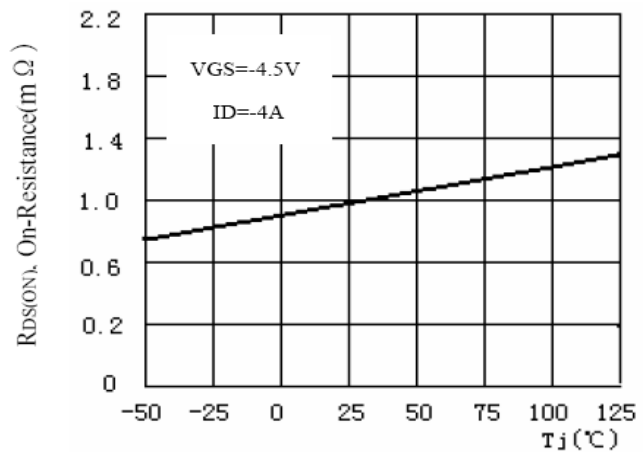
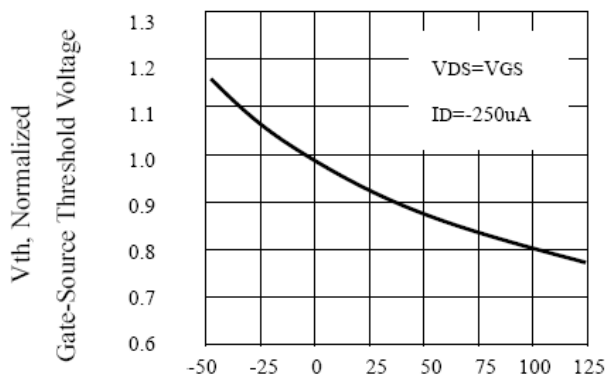
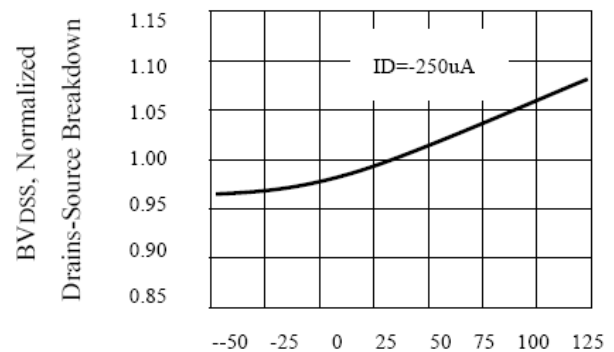


Figure4. On-Resistance Variation with Temperature



$T_j$ , Junction Temperature( $^\circ\text{C}$ )

Figure5. Gate Threshold Variation With Temperature



$T_j$ , Junction Temperature ( $^\circ\text{C}$ )

Figure6. Breakdown Voltage Variation With Temperature

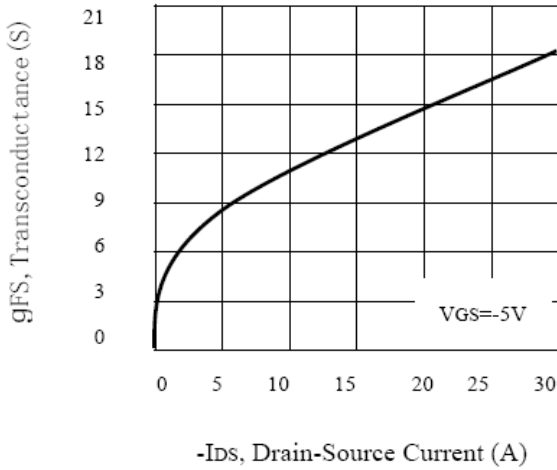


Figure 7. Transconductance Variation With Drain Current

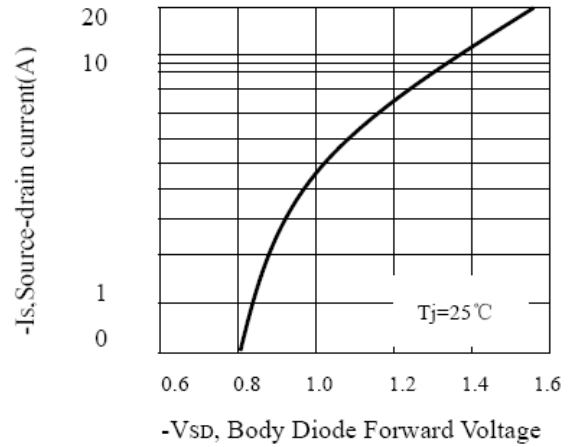


Figure 8. Body Diode Forward Voltage Variation with Source Current

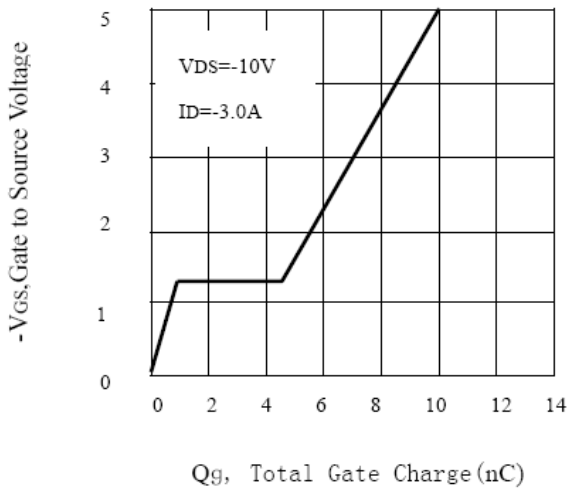


Figure 9. Gate Charge

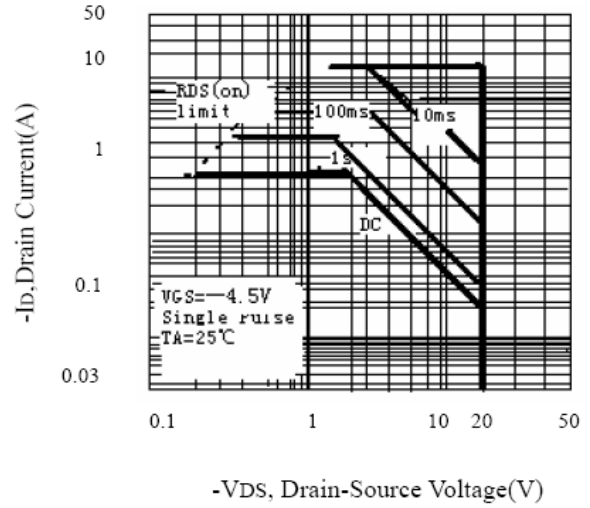
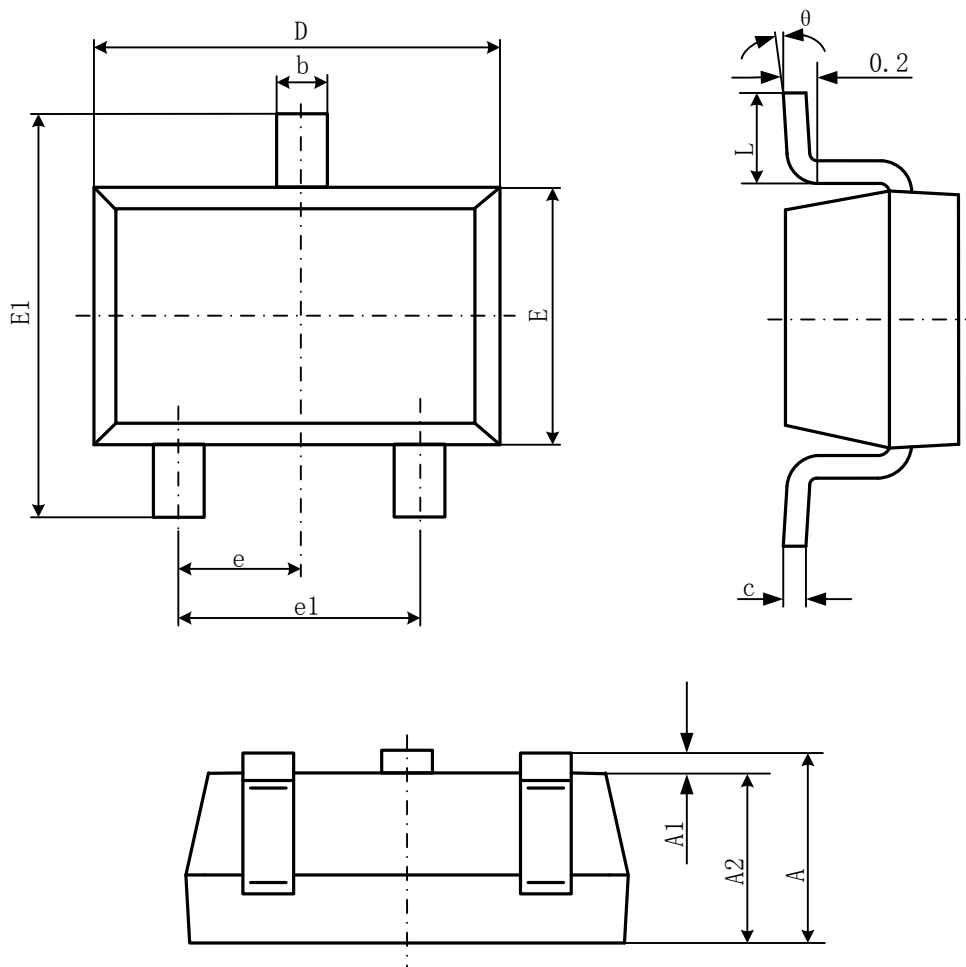


Figure 10. Maximum Safe Operating Area

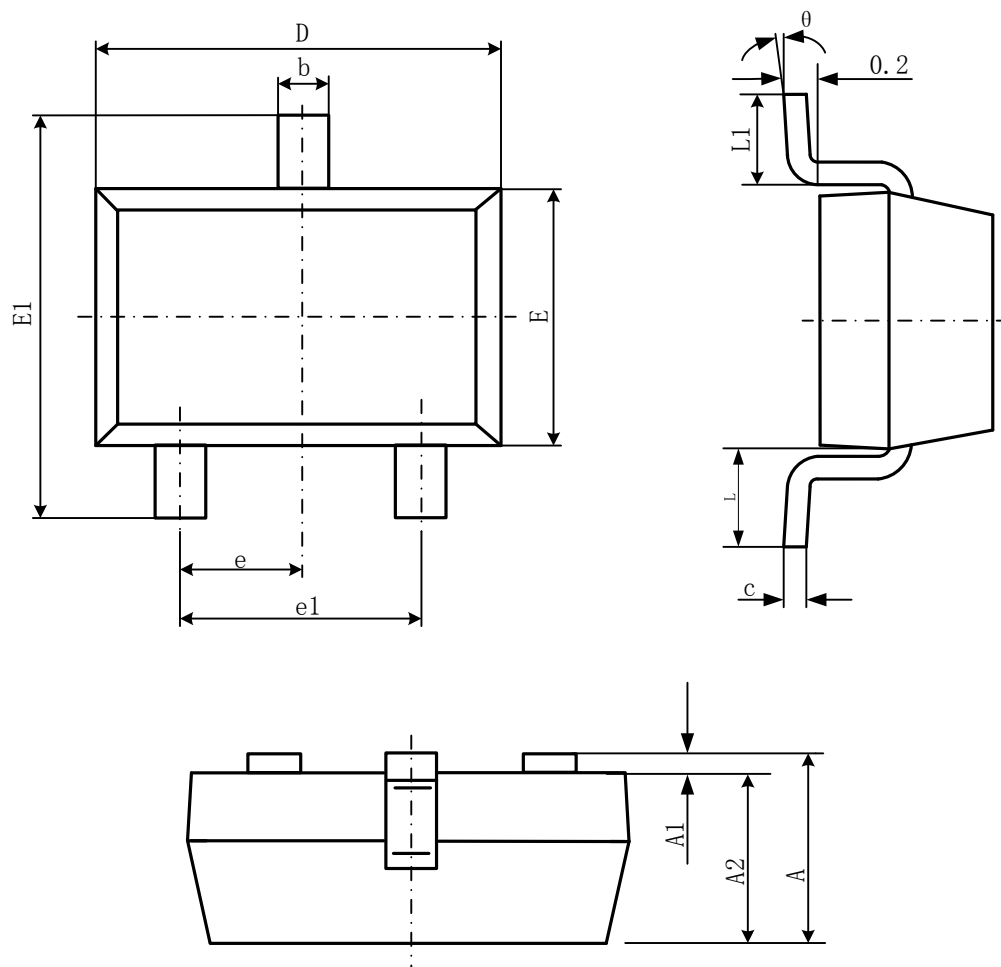
**■ 封装形式**

- SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

## ● SOT-23-3B



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.041	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.041	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.500	1.700	0.059	0.067
E1	2.250	2.550	0.089	0.100
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°